



COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET

Product Summary

Device	BV _{DSS}	RDS(ON) Max	I _{D MAX} T _A = +25°C
Q1	20V	$25m\Omega$ @ V _{GS} = 4.5V	
N-Channel	200	35mΩ @ V _{GS} = 2.5V	5.1A
Q2	201/	75mΩ @ V _{GS} = -4.5V	-3.5A
P-Channel	-20V	140mΩ @ V _{GS} = -2.5V	-2.5A

Features

- PCB Footprint of 4mm²
- Low On-Resistance
- Low Input Capacitance
- Low Profile, 0.6mm Maximum Height
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

Description and Applications

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, which makes it ideal for high-efficiency power management applications.

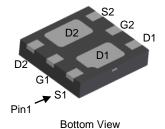
- Load Switch
- Power Management Functions
- Portable Power Adaptors

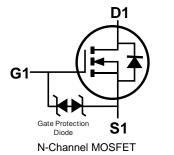
Mechanical Data

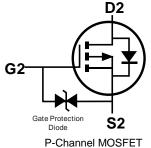
- Case: U-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @4
- Terminals Connections: See Diagram Below
- Weight: 0.0065 grams (Approximate)

U-DFN2020-6 (Type B)









Internal Schematic

Ordering Information (Note 4)

Part Number	Case	Packaging
DMC2025UFDB-7	U-DFN2020-6 (Type B)	3000/Tape & Reel
DMC2025UFDB-13	U-DFN2020-6 (Type B)	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



Marking Information

Site 1



O4 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: H = 2020) M = Month (ex: 9 = September)

Date Code Kev

Year	2017		2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	E		Н		J	K	L	М	N	0	Р	R
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

Site 2



O4 = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 0 = 2020) W = Week (ex: a = Week 27; z Represents Week 52 and 53) X = Internal Code (ex: U = Monday)

Date Code Key

Date Code Key												
Year	2017		2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	7		0	1	2	3	4	5	6	7	8	9
Week	M/I-				ı	07	F0					
Week		1	-26			27-52			53			
Code		A-Z a-z z				a-z			<u>'</u>			
Internal Code	Sun		Mon		Tue	W	ed	Thu		Fri		Sat
Code	Т		Ü		V	V	٧	Х		Υ		Z



Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Q1 N-CHANNEL	Q2 P-CHANNEL	Unit		
Drain-Source Voltage			VDSS	20	-20	V
Gate-Source Voltage				±10	±8	V
Continuous Drain Current (Note 6) N-Channel: V _{GS} = 4.5V P-Channel: V _{GS} = -4.5V	Steady State	T _A = +25°C T _A = +70°C	I _D	6.0 4.8	-3.5 -2.8	А
Maximum Continuous Body Diode Forward Cur	rent (Note 6)	Is	2	-1.0	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle =	I _{DM}	20	-10	Α		
Avalanche Current (L = 0.1mH) (Note 7)	las	8	-13	Α		
Avalanche Energy (L = 0.1mH) (Note 7)	•		Eas	8	8.5	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T _A = +25°C	PD	0.7	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	RөJA	178	°C/W
Total Power Dissipation (Note 6)	T _A = +25°C	P _D	1.4	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	RөJA	92	°C/W
Thermal Resistance, Junction to Case (Note 6)	Rелс	30	*C/VV	
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics Q1 N-CHANNEL (@ TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BVDSS	20	l	_	V	$V_{GS} = 0V, I_{D} = 250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	IDSS	_	-	1	μΑ	V _{DS} = 20V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	_	±10	μA	$V_{GS} = \pm 10V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	0.5	I	1.0	٧	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
Static Drain-Source On-Resistance	Descent		l	25	mΩ	$V_{GS} = 4.5V, I_{D} = 4A$	
Static Drain-Source Off-Resistance	RDS(ON)		I	35	11122	$V_{GS} = 2.5V, I_{D} = 4A$	
Diode Forward Voltage	VsD	_	0.7	1.2	V	$V_{GS} = 0V$, $I_{S} = 5A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C _{iss}		486			101/11/	
Output Capacitance	Coss		92		pF	$V_{DS} = 10V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	Crss	_	77	_		I = 1.0IVIHZ	
Gate Resistance	Rg	_	3.2	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Qg	_	5.9	_			
Total Gate Charge (V _{GS} = 10V)	Qg	_	12.3	_	nC	V _{DS} = 10V. I _D = 6.5A	
Gate-Source Charge	Qgs	_	0.8	_	IIC	VDS = 10V, ID = 6.5A	
Gate-Drain Charge	Q_{gd}	_	2.2	_			
Turn-On Delay Time	t _{D(ON)}	_	3.4	_			
Turn-On Rise Time	tR	_	5.4	_	no	$V_{DS} = 10V, V_{GS} = 4.5V,$	
Turn-Off Delay Time	tD(OFF)	_	17.6	_	ns	$R_g = 6\Omega$, $R_L = 10\Omega$, $I_D = 1A$	
Turn-Off Fall Time	tF	_	9.3	_			
Reverse Recovery Time	trr	_	7.7	_	ns	I _F = 1A, di/dt = 100A/μs	
Reverse Recovery Charge	Qrr		1.5	_	nC	I _F = 1A, di/dt = 100A/μs	

5. Device mounted on FR-4 substrate PCB, 2oz copper, with minimum recommended pad layout. Notes: 6. Device mounted on FR-4 substrate PCB, 2oz copper, with 1inch square copper plate.

^{7.} I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep T_J = +25°C.

^{8.} Short duration pulse test used to minimize self-heating effect.
9. Guaranteed by design. Not subject to product testing.



Electrical Characteristics Q2 P-CHANNEL (@ T_A = +25°C, unless otherwise specified.)

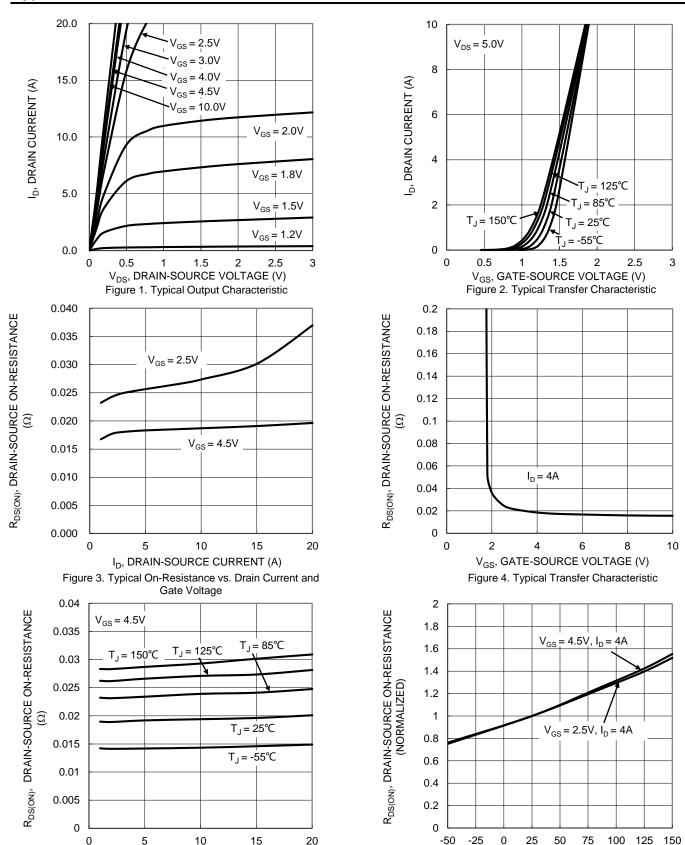
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV _{DSS}	-20	1	-	V	$V_{GS} = 0V, I_{D} = -250\mu A$
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	-1.0	μA	V _{DS} = -20V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	_	_	±10	μA	$V_{GS} = \pm 8V$, $V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V _{GS(TH)}	-0.35	1	-1.4	V	$V_{DS} = V_{GS}$, $I_D = -250\mu A$
Static Drain-Source On-Resistance	D	_		75	mΩ	VGS = -4.5V, I _D = -2.9A
Static Dialii-Source Off-Resistance	RDS(ON)	_	_	140	11122	Vgs = -2.5V, ID = -2.3A
Diode Forward Voltage	Vsp	_	_	-1.2	V	VGS = 0V, IS = -3.0A
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	Ciss		642	1	pF	101/11/
Output Capacitance	Coss	_	98	_	pF	V _{DS} = -10V, V _{GS} = 0V, f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	87	_	pF	1 = 1.000112
Gate Resistance	Rg	_	26.5	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge (V _{GS} = -4.5V)	0	_	8.8	_	nC	
Total Gate Charge (V _{GS} = -8V)	Q_g	_	15	_	nC	101/1 0.74
Gate-Source Charge	Q _{gs}	_	0.9	_	nC	$V_{DS} = -10V, I_{D} = -3.7A$
Gate-Drain Charge	Q _{gd}	_	2.9	_	nC	
Turn-On Delay Time	tD(ON)	_	5.5	_	ns	
Turn-On Rise Time	t _R	_	22.6	_	ns	V _{DD} = -10V, V _{GS} = -4.5V,
Turn-Off Delay Time	tD(OFF)	_	34.1		ns	$R_L = 3.3\Omega$, $R_g = 1\Omega$
Turn-Off Fall Time	tF	_	34.3	_	ns	
Body Diode Reverse Recovery Time	trr	_	13	_	ns	Is = -3.0A, dI/dt = 100A/µs
Body Diode Reverse Recovery Charge	Q _{RR}	_	3.3	-	nC	Is = -3.0A, dI/dt = 100A/µs

Notes: 8. Short duration pulse test used to minimize self-heating effect.

^{9.} Guaranteed by design. Not subject to product testing.



Typical Characteristics - N-CHANNEL



I_D, DRAIN CURRENT (A)

Figure 5. Typical On-Resistance vs. Drain Current

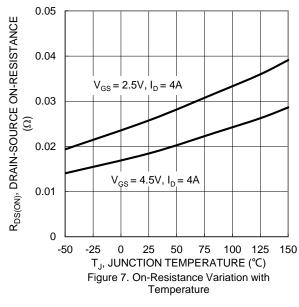
and Temperature

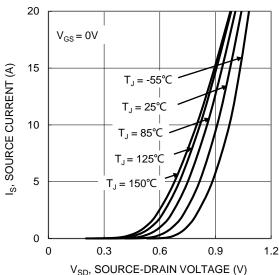
T_J, JUNCTION TEMPERATURE (°C)

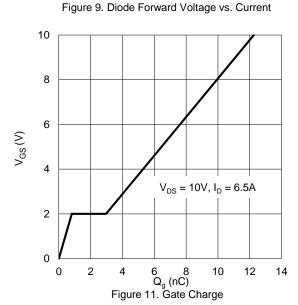
Figure 6. On-Resistance Variation with Temperature



Typical Characteristics - N-CHANNEL (continued)







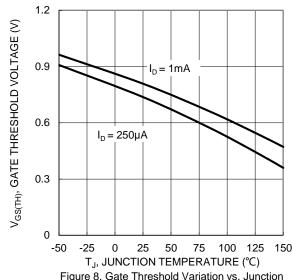


Figure 8. Gate Threshold Variation vs. Junction Temperature

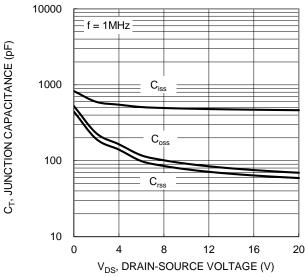
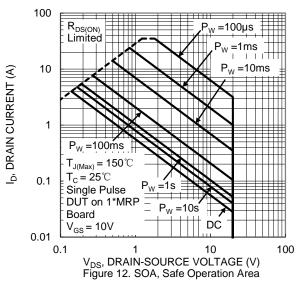
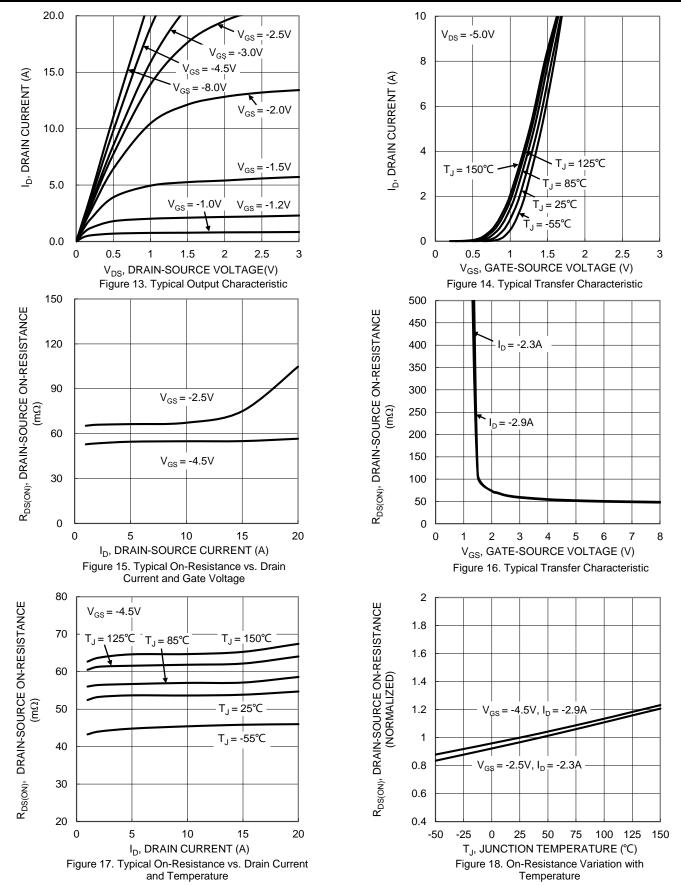


Figure 10. Typical Junction Capacitance



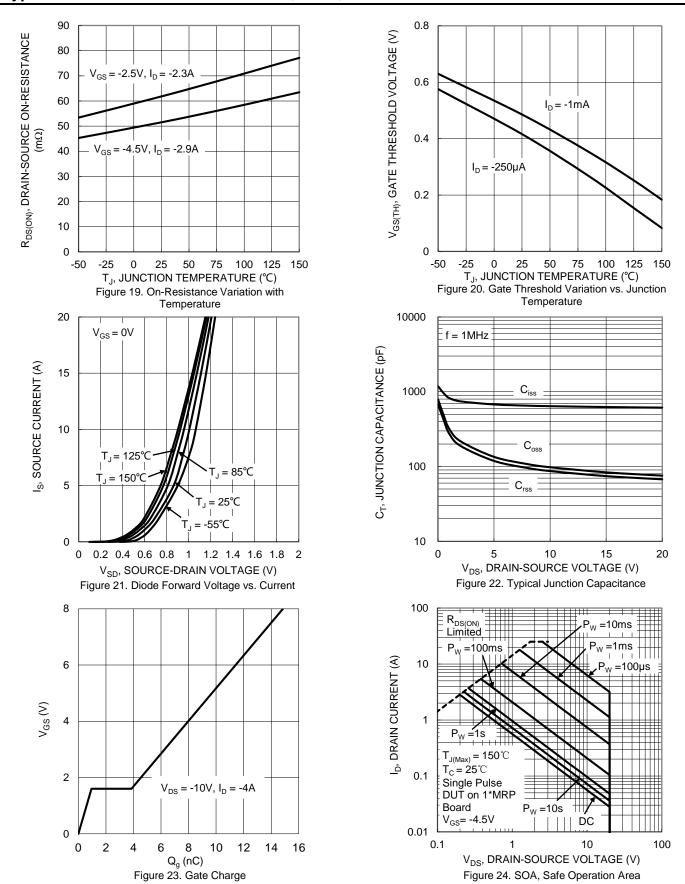


Typical Characteristics - P-CHANNEL





Typical Characteristics - P-CHANNEL (continued)





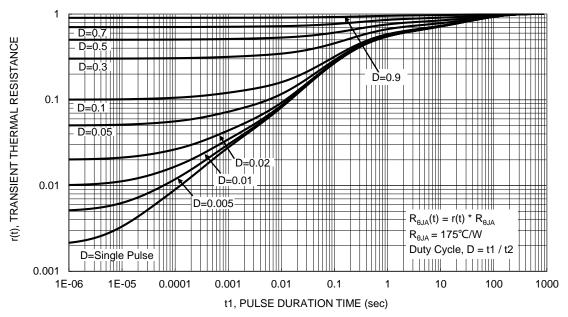


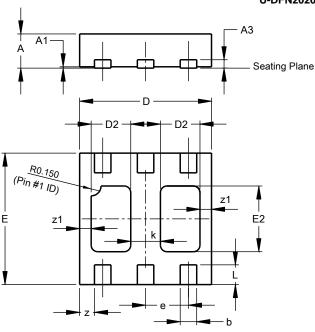
Figure 25. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type B)

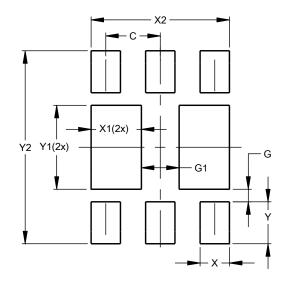


U-DFN2020-6 Type B							
Dim	Min	Max	Тур				
Α	0.545	0.605	0.575				
A1	0.00	0.05	0.02				
A3	_	_	0.13				
b	0.20	0.30	0.25				
D	1.95	2.075	2.00				
D2	0.50	0.70	0.60				
е	_	_	0.65				
Е	1.95	2.075	2.00				
E2	0.90	1.10	1.00				
k	_	_	0.45				
L	0.25	0.35	0.30				
Z	_	_	0.225				
z1		_	0.175				
All	Dimens	ions in	mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type B)



Dimensions	Value
פווטופווסוווט	(in mm)
С	0.650
G	0.150
G1	0.450
X	0.350
X1	0.600
X2	1.650
Y	0.500
Y1	1.000
Y2	2.300



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